

## Features

- Advanced high cell density Trench technology
- Super Low Gate Charge
- Excellent CdV/dt effect decline
- 100% EAS Guaranteed
- Green Device Available

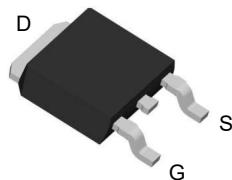
## Product Summary



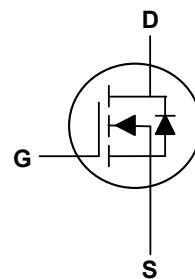
$V_{DS}$	80	V
$I_D$	100	A
$R_{DS(ON)}$ (at $V_{GS}=10V$ )	3.9	mΩ
$R_{DS(ON)}$ (at $V_{GS}=4.5V$ )	6.2	mΩ

## Applications

- High Frequency Point-of-Load,Synchronous Buck Converter
- Networking DC-DC Power System
- Load Switch, LED applications



TO-252 Top View



## Absolute Maximum Ratings( $T_c=25^\circ C$ , unless otherwise noted)

Parameter	Symbol	Rating	Units
Drain-Source Voltage	$V_{DS}$	80	V
Gate-Source Voltage	$V_{GS}$	+20/-12	V
Continuous Drain Current	$I_D @ T_c=25^\circ C$	100	A
Continuous Drain Current	$I_D @ T_c=100^\circ C$	63	A
Pulsed Drain Current <sup>2</sup>	$I_{DM}$	400	A
Single Pulse Avalanche Energy <sup>3</sup>	EAS	245	mJ
Avalanche Current	$I_{AS}$	70	A
Total Power Dissipation ( $T_c=25^\circ C$ )	$P_D$	130	W
Power Dissipation - Derate above 25°C		1.04	W/°C
Storage Temperature Range	$T_{STG}$	-55 to 150	°C
Operating Junction Temperature Range	$T_J$	-55 to 150	°C

## Thermal Characteristics

Parameter	Symbol	Typ	Max	Unit
Thermal Resistance Junction-Ambient <sup>1</sup>	$R_{\theta JA}$	---	62	°C/W
Thermal Resistance Junction-Case <sup>1</sup>	$R_{\theta JC}$	---	0.96	°C/W

**Electrical Characteristics ( $T_J=25^\circ\text{C}$ , unless otherwise noted)**

Parameter	Symbol	Conditions	Min	Typ	Max	Unit
Drain-Source Breakdown Voltage	$\text{BV}_{\text{DSS}}$	$V_{\text{GS}}=0\text{V}$ , $I_D=250\mu\text{A}$	80	---	---	V
$\text{BV}_{\text{DSS}}$ Temperature Coefficient	$\triangle \text{BV}_{\text{DSS}}/\triangle T_J$	Reference to $25^\circ\text{C}$ , $I_D=1\text{mA}$	---	0.03	---	$\text{V}/^\circ\text{C}$
Static Drain-Source On-Resistance <sup>2</sup>	$R_{\text{DS}(\text{ON})}$	$V_{\text{GS}}=10\text{V}$ , $I_D=20\text{A}$	---	3.2	3.9	$\text{m}\Omega$
		$V_{\text{GS}}=4.5\text{V}$ , $I_D=10\text{A}$	---	4.6	6.2	$\text{m}\Omega$
Gate Threshold Voltage	$V_{\text{GS}(\text{th})}$	$V_{\text{GS}}=V_{\text{DS}}$ , $I_D=250\mu\text{A}$	1.2	---	2.5	V
$V_{\text{GS}(\text{th})}$ Temperature Coefficient	$\triangle V_{\text{GS}(\text{th})}$		---	-5.8	---	$\text{mV}/^\circ\text{C}$
Drain-Source Leakage Current	$I_{\text{DSS}}$	$V_{\text{DS}}=80\text{V}$ , $V_{\text{GS}}=0\text{V}$ , $T_J=25^\circ\text{C}$	---	---	1	$\text{uA}$
		$V_{\text{DS}}=64\text{V}$ , $V_{\text{GS}}=0\text{V}$ , $T_J=85^\circ\text{C}$	---	---	10	
Gate-Source Leakage Current	$I_{\text{GSS}}$	$V_{\text{GS}}=20\text{V}$ , $V_{\text{DS}}=0\text{V}$	---	---	100	nA
Forward Transconductance	$g_{\text{fs}}$	$V_{\text{DS}}=10\text{V}$ , $I_D=5\text{A}$	---	10	---	S
Gate Resistance	$R_g$	$V_{\text{DS}}=0\text{V}$ , $V_{\text{GS}}=0\text{V}$ , $f=1\text{MHz}$	---	1.65	---	$\Omega$
Total Gate Charge	$Q_g$	$V_{\text{DS}}=64\text{V}$ , $V_{\text{GS}}=10\text{V}$ , $I_D=10\text{A}$	---	88	---	$\text{nC}$
Gate-Source Charge	$Q_{\text{gs}}$		---	10.2	---	
Gate-Drain Charge	$Q_{\text{gd}}$		---	24	---	
Turn-On Delay Time	$T_{\text{d}(\text{on})}$	$V_{\text{DD}}=40\text{V}$ , $V_{\text{GS}}=10\text{V}$ , $R_g=6\Omega$ , $I_D=1\text{A}$	---	20	---	$\text{ns}$
Rise Time	$T_r$		---	13	---	
Turn-Off Delay Time	$T_{\text{d}(\text{off})}$		---	36	---	
Fall Time	$T_f$		---	18	---	
Input Capacitance	$C_{\text{iss}}$	$V_{\text{DS}}=25\text{V}$ , $V_{\text{GS}}=0\text{V}$ , $f=1\text{MHz}$	---	5160	---	$\text{pF}$
Output Capacitance	$C_{\text{oss}}$		---	1346	---	
Reverse Transfer Capacitance	$C_{\text{rss}}$		---	40	---	

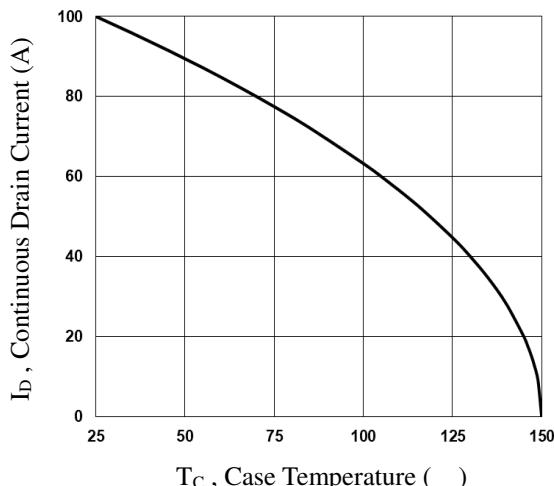
**Drain-Source Diode Characteristics**

Parameter	Symbol	Conditions	Min	Typ	Max	Unit
Continuous Source Current <sup>1,5</sup>	$I_s$	$V_G=V_D=0\text{V}$ , Force Current	---	---	100	A
Pulsed Source Current <sup>2,5</sup>	$I_{\text{SM}}$		---	---	200	A
Diode Forward Voltage <sup>2</sup>	$V_{\text{SD}}$	$V_{\text{GS}}=0\text{V}$ , $I_s=1\text{A}$ , $T_J=25^\circ\text{C}$	---	---	1	V

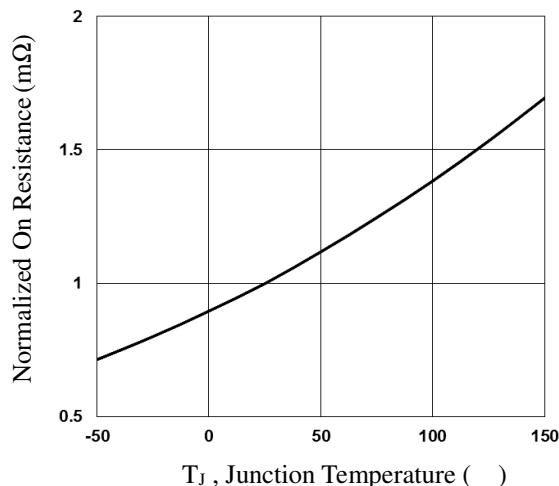
**Note:**

- 1.The data tested by surface mounted on a 1 inch<sup>2</sup> FR-4 board with 2OZ copper.
- 2.The data tested by pulsed , pulse width  $\leq 300\mu\text{s}$  , duty cycle  $\leq 2\%$
- 3.The EAS data shows Max. rating . The test condition is  $V_{\text{DD}}=25\text{V}$ , $V_{\text{GS}}=10\text{V}$ , $L=0.1\text{mH}$ , $R_g=25\Omega$ , $I_{\text{AS}}=70\text{A}$
- 4.The power dissipation is limited by  $150^\circ\text{C}$  junction temperature
- 5.The data is theoretically the same as  $I_D$  and  $I_{\text{DM}}$  , in real applications , should be limited by total power dissipation.

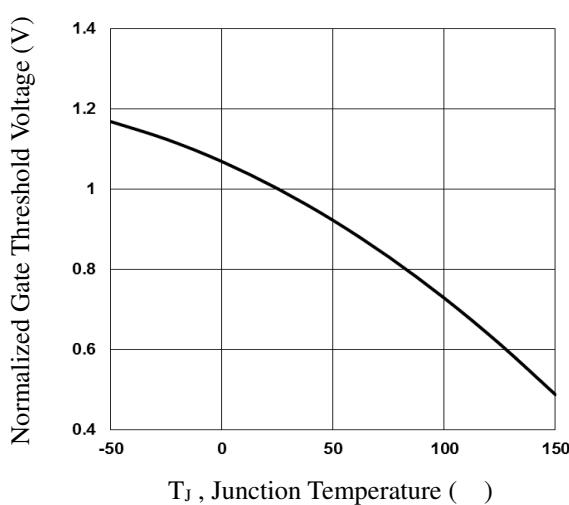
## Typical Characteristics



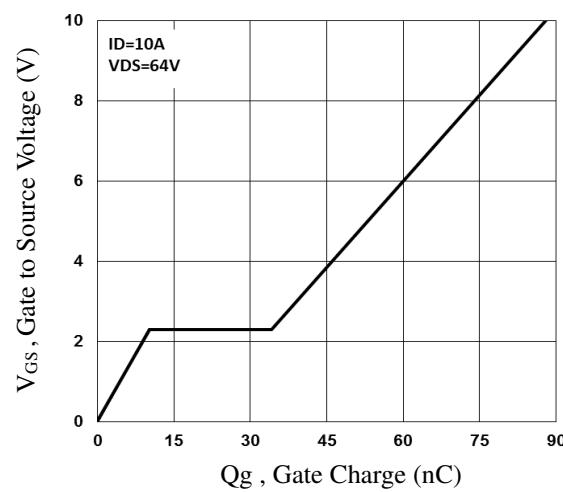
**Fig.1 Continuous Drain Current vs. T<sub>c</sub>**



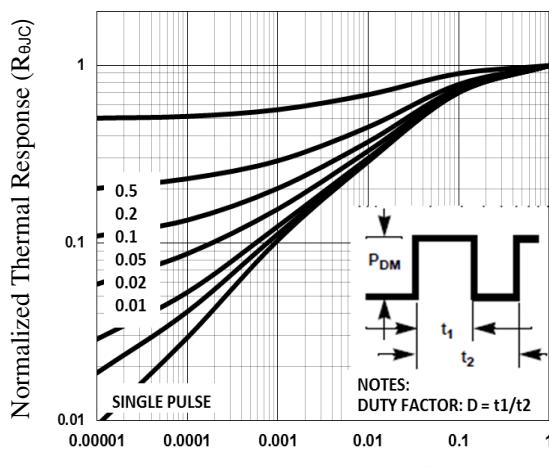
**Fig.2 Normalized RDS(on) vs. T<sub>j</sub>**



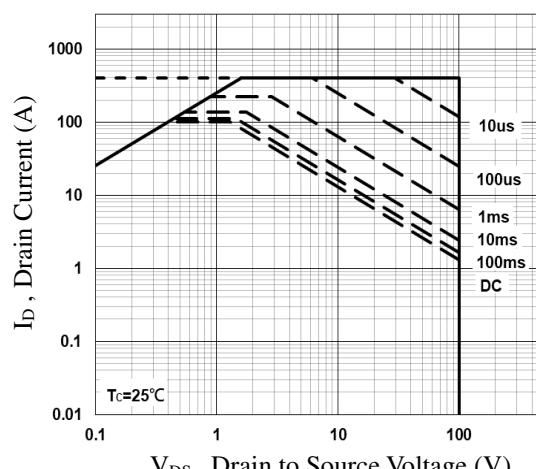
**Fig.3 Normalized V<sub>th</sub> vs. T<sub>j</sub>**



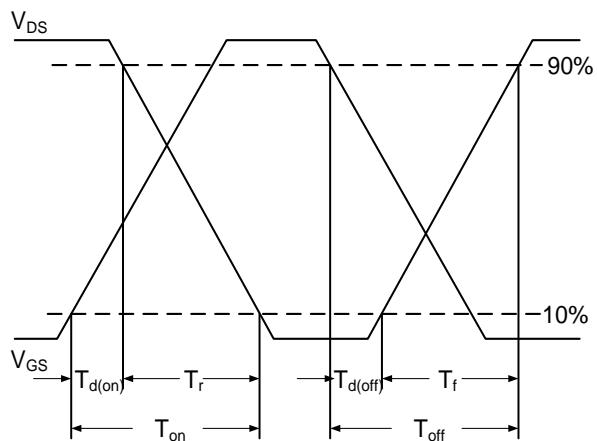
**Fig.4 Gate Charge Characteristics**



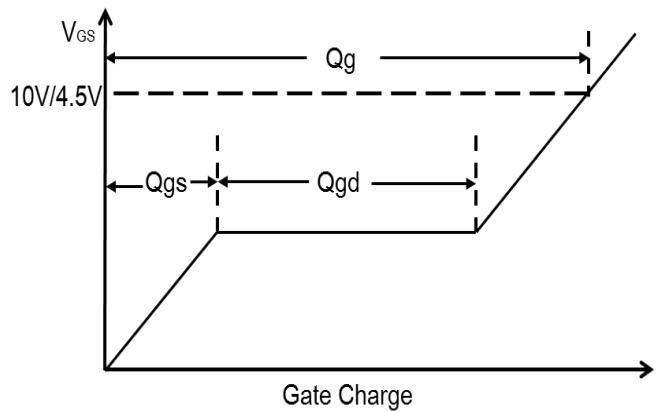
**Fig.5 Normalized Transient Impedance**



**Fig.6 Maximum Safe Operation Area**

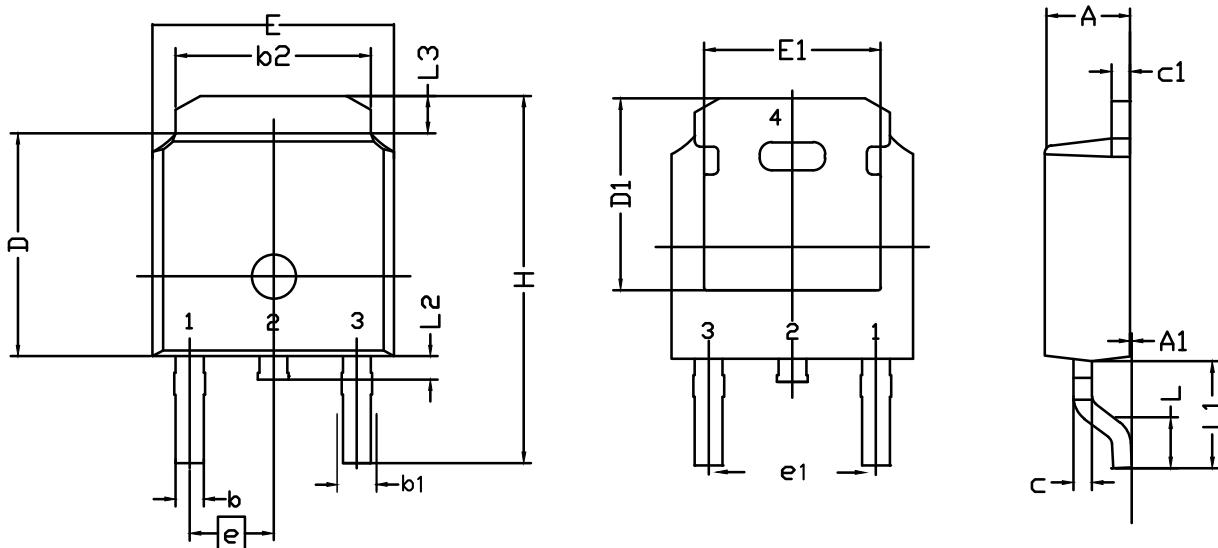


**Fig.7** Switching Time Waveform



**Fig.8** Gate Charge Waveform

### TO-252 Package Outline Dimensions



<b>Symbol</b>	<b>Dimensions (unit:mm)</b>			<b>Symbol</b>	<b>Dimensions (unit:mm)</b>		
	<b>Min</b>	<b>Typ</b>	<b>Max</b>		<b>Min</b>	<b>Typ</b>	<b>Max</b>
<b>A</b>	2.20	2.30	2.38	<b>E</b>	6.40	6.60	6.731
<b>A<sub>1</sub></b>	0.00	0.10	0.20	<b>E<sub>1</sub></b>	4.40	--	--
<b>b</b>	0.64	0.76	0.89	<b>e</b>	2.286 BSC		
<b>b<sub>1</sub></b>	0.77	0.85	1.14	<b>e<sub>1</sub></b>	4.572 BSC		
<b>b<sub>2</sub></b>	5.00	5.33	5.46	<b>H</b>	9.40	10.00	10.40
<b>c</b>	0.458	0.508	0.610	<b>L</b>	1.40	1.52	1.77
<b>C<sub>1</sub></b>	0.458	0.508	0.620	<b>L<sub>1</sub></b>	--	2.743	--
<b>D</b>	5.98	6.10	6.223	<b>L<sub>2</sub></b>	0.60	0.80	1.01
<b>D<sub>1</sub></b>	5.20	5.25	5.38	<b>L<sub>3</sub></b>	0.90	1.06	1.25